

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property  
Organization  
International Bureau

(43) International Publication Date  
23 April 2020 (23.04.2020)



(10) International Publication Number  
**WO 2020/078939 A1**

(51) International Patent Classification:

C09K 19/38 (2006.01) C09K 19/32 (2006.01)  
C09K 19/04 (2006.01) C09K 19/34 (2006.01)  
C09K 19/20 (2006.01)

Published:

— with international search report (Art. 21(3))

(21) International Application Number:

PCT/EP2019/077837

(22) International Filing Date:

15 October 2019 (15.10.2019)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:

18201357.3 18 October 2018 (18.10.2018) EP  
18205766.1 12 November 2018 (12.11.2018) EP

(71) Applicant: **MERCK PATENT GMBH** [DE/DE]; Frankfurter Strasse 250, 64293 DARMSTADT (DE).

(72) Inventors: **LARBIG, Gregor**; Hauptstrasse 3, 63571 GELNHAUSEN (DE). **MISKIEWICZ, Pawel**; Bahnhofstrasse 64, 63263 NEU-ISENBURG (DE). **MEYER, Frank**; Hoehenblick 7a, 61479 GLASHUETTEN (DE). **PAHNKE, Joerg**; Praelat-Diehl-Strasse 27, 64285 DARMSTADT (DE). **KOPPE, Karsten**; Borsdorffstrasse 2a, 64289 DARMSTADT (DE).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

(54) Title: DIELECTRIC COPOLYMER MATERIALS

(57) Abstract: The present invention relates to a polymerizable mixture which can be used to form a dielectric material for the preparation of passivation layers in electronic devices. The polymerizable mixture comprises a first monomer and a second monomer which may react to form a copolymer providing excellent film forming capability, excellent thermal properties and excellent mechanical properties. There is further provided a method for forming said copolymers and an electronic device containing said copolymers as dielectric material. Beyond that, the present invention relates to a manufacturing method for preparing a packaged microelectronic structure and to a microelectronic device comprising said packaged microelectronic structure formed by said manufacturing method.

WO 2020/078939 A1